Tz-Cheng Chiu

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/2009928/publications.pdf

Version: 2024-02-01

28	227	1307594 7	1058476 14
papers	citations	h-index	g-index

28	28	28	127
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Warpage simulation for the reconstituted wafer used in fan-out wafer level packaging. Microelectronics Reliability, 2018, 80, 14-23.	1.7	47
2	Analysis of stress intensity factors for three-dimensional interface crack problems in electronic packages using the virtual crack closure technique. International Journal of Fracture, 2009, 156, 75-96.	2.2	33
3	Effects of Curing and Chemical Aging on Warpageâ€"Characterization and Simulation. IEEE Transactions on Device and Materials Reliability, 2011, 11, 339-348.	2.0	20
4	Warpage evolution of overmolded ball grid array package during post-mold curing thermal process. Microelectronics Reliability, 2011, 51, 2263-2273.	1.7	17
5	Ball Grid Array Solder Joint Reliability Under System-Level Compressive Load. IEEE Transactions on Device and Materials Reliability, 2010, 10, 324-337.	2.0	13
6	Using DMA to Simultaneously Acquire Young's Relaxation Modulus and Time-dependent Poisson's Ratio of a Viscoelastic Material. Procedia Engineering, 2014, 79, 153-159.	1.2	12
7	On the mechanics of laser peeling for ultra-thin glasses. Engineering Fracture Mechanics, 2016, 163, 236-247.	4.3	8
8	A Mechanics Model for the Moisture Induced Delamination in Fan-Out Wafer-Level Package. , 2020, , .		8
9	On the Homogenization of Multilayered Interconnect for Interfacial Fracture Analysis. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 388-398.	1.3	7
10	Reliability model for bridging failure of Pb-free ball grid array solder joints under compressive load. Microelectronics Reliability, 2010, 50, 2037-2050.	1.7	7
11	Temperature distribution and heat flow around a crack of arbitrary orientation in a functionally graded medium. Journal of Engineering Mathematics, 2014, 87, 123-137.	1.2	7
12	Analysis of fatigue delamination growth in flip-chip package. Acta Mechanica, 2014, 225, 2761-2773.	2.1	6
13	Thermo-mechanical analysis of laser peeling of ultrathin glass for removing edge flaws in web processing applications. Microsystem Technologies, 2018, 24, 397-409.	2.0	6
14	A unified viscoplastic model for characterizing the softening behavior of the Sn3.0Ag0.5Cu solder under monotonic and cyclic loading conditions. Microelectronics Reliability, 2021, 119, 114086.	1.7	6
15	Physical Aging of Epoxy Molding Compound and Its Influences on the Warpage of Reconstituted Wafer. , 2018, , .		5
16	Coupled Hygro-Thermo-Mechanical Analysis of Moisture Induced Interfacial Stresses in Fan-Out Package. , 2019, , .		5
17	A numerical procedure for simulating delamination growth on interfaces of interconnect structures. Microelectronics Reliability, 2012, 52, 1464-1474.	1.7	4
18	Time-domain viscoelastic constitutive model based on concurrent fitting of frequency-domain characteristics. Microelectronics Reliability, 2015, 55, 2336-2344.	1.7	4

#	Article	IF	Citations
19	An experimental setup for characterizing subcritical debonding of materials interface under mixed mode fatigue loading. International Journal of Fatigue, 2018, 114, 109-119.	5.7	3
20	A Viscoplastic-Based Fatigue Reliability Model for the Polyimide Dielectric Thin Film. , 2019, , .		3
21	Three dimensional corner delamination analysis for fan-out chip scale package. , 2008, , .		2
22	Evaluation of Strain Measurement in a Die-to-Interposer Chip Using In Situ Synchrotron X-Ray Diffraction and Finite-Element Analysis. Journal of Electronic Materials, 2014, 43, 52-56.	2.2	2
23	Development and Application of the Moisture-Dependent Viscoelastic Model of Polyimide in Hygro-Thermo-Mechanical Analysis of Fan-Out Interconnect. , 2022, , .		2
24	Analysis of flip-chip corner delamination using 3-D virtual crack closure technique. , 2008, , .		0
25	Simultaneously obtaining the Young's relaxation modulus and shear relaxation modulus of an epoxy molding compound by using DMA. , 2014, , .		0
26	A Novel Experimental System for Characterizing Interface Delamination under Mixed-Mode Fatigue Loading. , 2016, , .		0
27	Development of consistent interconversions between linear viscoelastic functions for multiaxial viscoelastic models. , 2017, , .		0
28	Fatigue Crack Growth on the Interface of Copper and Epoxy Molding Compound under Mixed-Mode Loading. , 2018, , .		0